

L Number	Hits	Search Text	DB	Time stamp
1	5	underbump adj metal adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:45
2	1	underbump adj barrier adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:49
3	61861	barrier adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:49
4	1080	metal adj barrier adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:49
5	83324	bump\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 11:50
6	60	(metal adj barrier adj layer) and bump\$1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:10
7	165035	support adj member	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:11
8	17775	second adj area	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:11
9	410	(support adj member) and (second adj area)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:11
10	1705364	substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:11
11	80	((support adj member) and (second adj area)) and substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:12
12	10	((((support adj member) and (second adj area)) and substrate) and bump	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/04/16 15:12

EAST - [thinsearch15.wsp:1]

FileViewEditToolsWindowHelp

L1: (2) "6683369"

L2: (4) "2003017654"

L3: (2) "20030017654"

L4: (17775) second adj area

L5: (30381) second adj region

L6: (1705364) substrate

L7: (4119) resin adj support

L8: (7) 5 and 6 and 7

L9: (5003) support adj pad

L10: (13405) BGA

L11: (165035) support adj member

L12: (560) 5 and 11

L13: (56) 12 and package

L14: (1362019) semiconductor

L15: (20) 13 and 14

L16: (0) resin adj dummy adj bump

L17: (167) dummy adj bump

L18: (113) 14 and 17

L19: (47488) 4 5

L20: (2) 18 and 19

L21: (37) 17 and resin

L22: (122) resin adj bump

L23: (89) 14 and 22

L24: (2) 23 and dummy

L25: (0) plastic adj dummy adj bump

L26: (2) 17 near resin

L27: (114) resin adj support adj member

L28: (16) 14 and 27

L29: (60) epoxy adj spacer

L30: (2) epoxy adj dummy

USPAT: US POPUB: EPO: IPO: DERWENT: BM: 108

Default operator: GR

"6175157"

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	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Cla	Inventor	S	C	P	3	Image 1
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6590286 B2	20030708	12	Land grid array semiconductor device	257/737	257/738; 257/780;		Okada, Makio et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6590
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6583512 B2	20030624	27	Semiconductor device and method for fabricating the same	257/777	257/666; 257/675;		Nakaoka, Yukiko et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6583
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6537855 B2	20030325	7	Semiconductor device and method of manufacturing the same	438/118	257/E21.503; 257/E21.514;		Taguchi, Yutaka et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6537
4	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6483190 B1	20021119	22	Semiconductor chip element, semiconductor chip element mounting	257/737	257/690; 257/734;		Kainuma, Norio et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6483
5	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6462420 B2	20021008	9	Semiconductor chip and semiconductor device having a chip-	257/777	257/786; 257/E23.021;		Hikita, Junichi et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6462
6	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6426559 B1	20020730	7	Miniature 3D multi-chip module	257/777	257/666; 257/685;		Bryan, Robert Newell et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6426
7	<input type="checkbox"/>	<input type="checkbox"/>	US 6424033 B1	20020723	12	Chip package with grease heat sink	257/718	257/E21.503;		Akram, Salman	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6424

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L29: (60) epoxy adj spacer

L30: (2) epoxy adj dummy

L31: (8) 29 and 14

L32: (122) resin adj bump

L33: (12) plastic adj bump

L34: (37) epoxy adj bump

L35: (30) 14 and 34

L36: (18) dummy adj plastic

L37: (631) resin adj spacer

L38: (68) 14 and 37

L39: (11) 38 and package

L40: (1) 10 and 37

L41: (6) "6208022"

L42: (14744) flexible adj substrate

L43: (7) 17 and 42

L44: (68) support adj bump

L45: (39) 44 and semiconductor

L46: (60308) supporting adj member

L47: (172) 46 and 42

L48: (478) supporting adj spacer

L49: (1) 48 and 42

L50: (0) 48 and semiconductor and package

L51: (25) 48 and semiconductor

L52: (9) "5635756"

L53: (11) "6175157"

DB: USPAT; US PGPUH; EPO; JPO; DERWENT; BM; 108

Default operator: OR

"6175157"

Plus

Highlight all terms in body

SRG term

SGR term

Image

Text

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	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Retrieval Cla	Inventor	S	C	P	NUM	Image 1
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6590286 B2	20030708	12	Land grid array semiconductor device	257/737	257/738; 257/780;		Okada, Makio et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6590
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6583512 B2	20030624	27	Semiconductor device and method for fabricating the same	257/777	257/666; 257/675;		Nakaoka, Yukiko et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6583
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6537855 B2	20030325	7	Semiconductor device and method of manufacturing the same	438/118	257/E21.503; 257/E21.514;		Taguchi, Yutaka et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6537
4	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6483190 B1	20021119	22	Semiconductor chip element	257/737	257/690;		Kanuma, Norio et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6483
5	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6462420 B2	20021008	9	Semiconductor chip and semiconductor device having a chip	257/777	257/734; 257/786;		Hikita, Junichi et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6462
6	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6426559 B1	20020730	7	Miniature 3D multi-chip module	257/777	257/E23.021; 257/666;		Bryan, Robert Newell et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6426
7	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6424033 B1	20020723	12	Chip package with grease heat sink and method of making	257/718	257/E21.503; 257/E23.087;		Akram, Salman	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6424
8	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6376914 B2	20020423	10	Dual-die integrated circuit package	257/777	257/666; 257/685;		Kovats, Julius A. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6376
9	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6285084 B1	20010904	14	Semiconductor device	257/777	257/80; 257/91;		Hikita, Junichi et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	US 6285

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DB: USPAT; US PGPUB; EPO; JPO; DERWENT; IBM; TOB

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